

DERWENT-ACC-NO: 2000-188081
DERWENT-WEEK: 200017
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TITLE: Printed wiring board for surface mounting of ball grid array package, has solder resist covering peripheral land leaving the rest opened with vent in elliptical shape reducing diameter of land

PATENT-ASSIGNEE: NEC CORP[NIDE]

PRIORITY-DATA: 1998JP-0197255 (July 13, 1998)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE
PAGES	MAIN-IPC	
JP 2000031631	January 28, 2000	N/A
007	H05K 003/34	
A		

APPLICATION-DATA:

PUB-NO	APPL-DESCRIPTOR	APPL-NO
APPL-DATE		
JP2000031631A	N/A	1998JP-0197255
July 13, 1998		

INT-CL (IPC): H05K003/34

ABSTRACTED-PUB-NO: JP2000031631A

BASIC-ABSTRACT: NOVELTY - The solder resist covers the periphery of the circular land and leaves the rest open. The vent of the solder resist is made into an ellipse making the diameter of land a short axis.

USE - For mother board containing surface mounted ball grid array package and chip size package.

ADVANTAGE - High density mounting of the wiring is achieved.

DESCRIPTION OF

DRAWING(S) - The figure shows the top view expanding and showing principal part of printing wiring board.

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CHOSEN-DRAWING: Dwg.1/10

TITLE-TERMS:

PRINT WIRE BOARD SURFACE MOUNT BALL GRID ARRAY PACKAGE SOLDER
RESIST COVER
PERIPHERAL LAND LEAVE REST OPEN VENT ELLIPSE SHAPE REDUCE
DIAMETER LAND

DERWENT-CLASS: V04

EPI-CODES: V04-R04A;

SECONDARY-ACC-NO:

Non-CPI Secondary Accession Numbers: N2000-139590